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(54) Title: METHOD FOR MAKING MULTILAYER THIN-FILM ELECTRONICS

(57) Abstract

Multilayer thin-film electronics are manufactured at high speed, even while the various component functions are manufactured separately under conditions tailored to optimize component performance and yield. Each function or group of functions is fabricated on a separate flexible substrate. These flexible substrates are bonded to each other using adhesive films that are anisotropic electrical conductors or optical light guides. The bonding is performed by laminating the flexible substrates to each other in a continuous process, using the anisotropic conductor as the bonding layer.